

Item	Standard	Advanced
Minimum Line/Spacing, Internal	3/3	3/3
Minimum Line/Spacing, External	4/4	3/3
Minimum Drilled Hole Size	8	6
Aspect Ratio (Thickness to Drill)	10:1	15:1
Annular Ring (Diameter over Drill)	10	8
Anti-pad (Diameter over Drill)	20	16
Plated Hole Tolerance	±3	±2
Minimum Dielectric Thickness	3	2
Maximum PCB Thickness (inches)	0.200	0.250
Thickness Tolerance (% of Thickness)	±10	±7
Maximum PCB Dimensions (inches)	16.0 X 22.0	30.0 X 44.0
Fabricated Dimensions - NC Routing	±5 mils	±3
Layer-to-Layer Registration Tolerance	±5	±3
Solder Mask Clearance, Per Side	2.0 mils	1.5 mils
Blind/Buried Vias (All Types)	yes	yes
Via Fill (Conductive, Non-Conductive)	no	yes

Inner Layers	Standard	Advanced
Minimum Core thickness	3 mils	2 mils
Minimum Line width	4 mils	3 mils (H Oz copper)
Minimum Spacing (Air gap)	4 mils	3 mils (H Oz copper)
Minimum pad size	Drill size +10 mils	Drill size +7 mils
Minimum Anti Pad (planes)	Drill size +20 mils	Drill size +16 mils

Outer Layers	Standard	Advanced
Max. Finished Thickness	0.200	0.250
Thickness Tolerance	±10%	±5%
Max. Aspect Ratio	10:1	12:1
Min. Drill Size	10 mils	8 mils
Min. Line width	4 mils	3 mils
Min. Spacing (air gap)	4 mils	3 mils
Min. Solder mask clearance	4 mils	3 mils
Min. solder mask web thickness	4 mils	3.4 mils